VISITECH BRINGS YIELD AND PRECISION TO SEMICON WEST

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Are you looking for the ultimate subsystem, enabling your next-generation direct imaging tool to perform in high-yield and high-precision applications? On December 7-9, Visitech welcomes you to Semicon West in San Francisco, displaying state-of-the-art subsystems for Semicon and advanced packaging industries at booth 439. We hope to see you there!

We're excited to tell you more about our LUXBEAM® Lithography System (LLS), which will be on display at the show. With our broad experience with Semicon, PCB, and additive manufacturing, we've succeeded in uniting cutting-edge optical, hardware, and software design in an ideal and flexible package. This high-resolution direct imaging subsystem uses patented optical multiplexing technology, yielding high throughput capability at low ownership cost – with a superior lifetime. The LLS range specifically targets machine builders in Semicon-related industries, providing line/space from 2.5 µm to 30 µm.

For companies looking at using DI (direct imaging) for their applications, Visitech is the ideal industry partner – providing DI subsystems with multiple advantages over traditional steppers for applications such as FOPLP, FOWLP, and SiP.

Our on-site team hopes to see you in San Francisco! You may pre-book a meeting with us here or browse our **LUXBEAM® Lithography System brochure** at your convenience.

Please use the form below if you want to pre-book a meeting with our team at Semicon West: